

WHAT IS CLAIMED IS:

1. A nonvolatile semiconductor memory package comprising:
 - a memory device having a memory cell array including a plurality of nonvolatile semiconductor memory cells;
 - a control portion configured to control the memory device;
 - a network interface connectable to a network;
 - a file management portion connected to the network interface configured to manage a relationship between a data file given from the network and an address of the memory cell array; and
 - a memory interface connected to the file management portion configured to convert a signal given from the network to a signal which is capable of being used at the control portion,wherein the package is wrapped by an insulating material.
2. The nonvolatile semiconductor memory package according to claim 1, wherein the network interface corresponds to a transmission control protocol/internet protocol.
3. The nonvolatile semiconductor memory package according to claim 2, wherein the network interface is connectable to the network by using a file transfer protocol.
4. The nonvolatile semiconductor memory package according to claim 2, wherein the network interface is connectable to the network by using an anonymous file transfer protocol.

5. The nonvolatile semiconductor memory package according to claim 2, wherein the network interface is connectable to the network by using a point-to-point protocol.

6. The nonvolatile semiconductor memory package according to claim 1, wherein the package is also connectable to equipment disconnected from the network.

7. The nonvolatile semiconductor memory package according to claim 6, wherein the package works as a storage device for the equipment.